DATA IMAGE CORPORATION

LCD Module Specification

ITEM NO.: CM160200SFAYB-01

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	2002/8/26		26

2. RECORD OF REVISION

Rev	Date	Item	Page	Comment
В	26/AUG/02	11.2.3, 11.3	21-22	1.Change: 11.2.3 Inspection Parameters. 2.Add:11.3 Sampling Condition.
B	26/AUG/02 26/AUG/02	11.2.3, 11.3 13	21-22 23	1.Change: 11.2.3 Inspection Parameters. 2.Add:11.3 Sampling Condition. New model numbering system update from old P/N# CM1621S1LYH-J2

3. GENERAL SPECIFICATION

Display Format :	16characters (W) \times 2lines (H)	
Character Size :	4.84 (W) × 8.06 (H) mm	
View Area :	99 (W) × 24 (H) mm	
General Dimensions :	122 (W) \times 44 (H) \times 14.5 (T) mm Ma	Х.
Weight :	76 g max.	
LCD Type :	STN Gray VSTN Yellow FSTN	
Polarizer mode :	Reflective V Transflective	
	Transmissive Negative	
View Angle :	V 6 O'clock 12 O'clock Others	
Backlight :	VLED EL CCFL	
Backlight Color :	V Yellow green Amber Blue Green	
	White Others	
Controller / Driver : Temperature Range :	KS0066 Normal V Wide Temperature Operating 0 to 50°C Operating -20 to 70°C Storage -20 to 70°C Storage -30 to 80°C	

4. ABSOLUTE MAXIMUM RATINGS

4.1 ELECTRICAL ABSOLUTE MAXIMUM RATINGS

			Vss=	$0V, Ta = 25^{\circ}$
Item	Symbol	Min.	Max.	Unit
Supply Voltage (Logic)	VDD-VSS	0	7	V
Supply Voltage (LCD Driver)	VDD-VEE	1.5	13.5	V
Input Voltage	VI	Vss	Vdd	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Tstg	-30	80	°C

4.2 ENVIRONMENTAL ABSOLUTE MAXIMUM RATINGS

Item	Operating		Sto	rage	Comment	
nem	(Min.)	Max.)	(Min.)	(Max.)	Comment	
Ambient Temp	-20	70	-30	80	Note (1)	
Humidity	Note (2)		Note(2)		Without Condensation	
Vibration		4.9M/S ²		19.6M/S ²	XYZ Direction	
Shock		29.4M/S ²		490M/S ²	XYZ Direction	

Note(1) Ta = $0^{\circ}C$: 50Hr Max.

Note(2) Ta $\leq 40^{\circ}$ C : 90% RH Max.

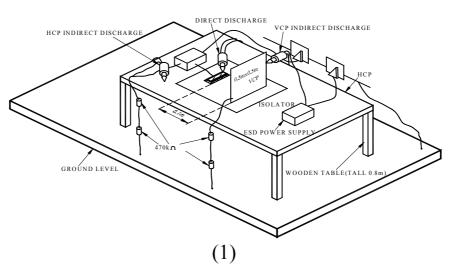
Ta $\geq 40^{\circ}$ C : Absolute humidity must be lower than the humidity of 90% RH at 40°C.

4.3 Electronic Static Discharge maximum rating

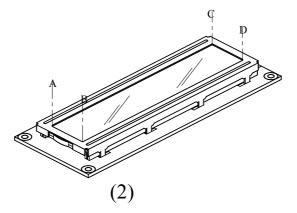
Item	Description			
Testing environment	Ambient temperature :15°C to 35 °C			
	Humidity: 30% to 60 %			
	LCM (E.U.T)) : Power up		
Testing equipment	Manufacture: NoiseKen, Model No. ESD-100L			
Testing condition	See drawing 1			
Direct discharge	0 to \pm 6 KV	Discharge point, see drawing 2		
Indirect discharge	0 to ± 12 KV	Discharge point, see drawing 1		
Pass condition	No malfunction of unit. Temporary malfunction of unit which			
	can be recovered by system reset			
Fail condition	Non. Recovera	ble malfunction of LCM or system		

ESD test method : IEC1000-4-2

FIG 1 ESD TESTING EQUIPMENT



DIRECT CONTACT DISCHARGE CONTACT POINT : A.B.C.D



Current

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply Voltage (Logic)	VDD-VSS		2.7	5.0	5.5	V
Supply Voltage (LCD)	VDD-VEE	-20°C	4.4	4.8	5.0	V
		25°C	4.2	4.5	4.8	
(200)		70°C	3.4	3.7	4.1	
Input Voltage	Vін		0.7*Vdd		Vdd	V
input voitage	VIL		Vss		0.3*Vdd	v
Logic Supply	IDD	VDD-VSS=5V		2.0		mA

5. **ELECTRICAL CHARACTERISTICS**

6. ELECTRO-OPTICAL CHARACTERISTICS

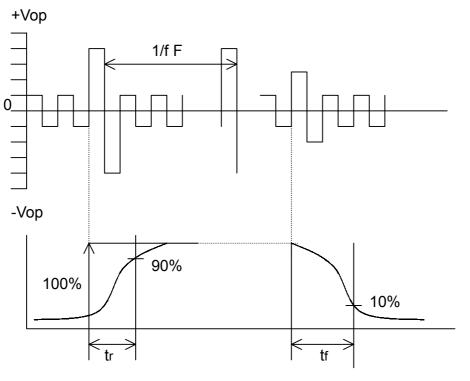
ITEM	Symbol	Condition	Min.	Тур.	Max.	Unit	Ref.
Diao Timo	Tr	0°C		1100	1800		
Rise Time	11	25°C		420	670	ms	Note (1)
Fall Time	Tf	0°C		210	340	me	Note (1)
	11	25°C		100	300	ms	
Contrast	CR	25°C		6			Note (3)
View Angle	θ1~θ2	25°C &		80			Note (2)
	Ø1, Ø2	CR≧2		30			Note (2)
Frame Frequency	Ff	25°C		64		Hz	

Note (1) & (2) : See next page

Note (3): Contrast ration is defined under the following condition:

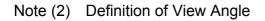
- CR= Brightness of non-selected condition Brightness of selected condition
- Temperature ----- 25°C (a).
- Frame frequency ---- 64Hz (b).
- Viewing angle ----- $\theta = 0^{\circ}$, $\emptyset = 0^{\circ}$ (C).
- Operating voltage --- 4.5V (d).

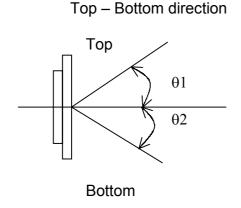
Note (1) Response time is measured as the shortest period of time possible between the change in state of an LCD segment as demonstrated below:



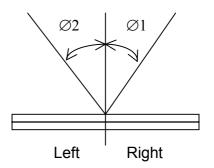
Condition:

- (a). Temperature -----25°C
- (b). Frame frequency ----- 64Hz
- (c). View Angle ----- $\theta = 0^\circ, \emptyset = 0^\circ$
- (d). Operating voltage ------ 4.5V





Right -- Left direction



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6.1 LED ELECTRO-OPTICAL CHARACTERISTIC

 $Ta = 25^{\circ}C$

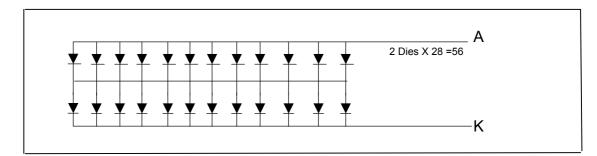
						1a - 25 C
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF = 280mA Yellow Green	-	4.2	4.6	V
Luminous Intensity	Iv	IF = 280mA Yellow Green	70	140		cd/m ²
Peak Emission	λP	IF = 280mA Yellow Green		570		nm
Spectrum Radiation	Δλ	IF = 280mA Yellow Green		30		nm
Reverse Current	IR	VR = 8V Yellow Green			0.2	mA

Note : Measured at the bared LED backlight unit.

6.2 LED MAXIMUM OPERATING RANGE

Item	Symbol	Yellow Green	Unit
Power Dissipation	Pad	1.8	W
Forward Current	laf	420	mA
Reverse Voltage	VR	8	V

6.2.1 LED ARRAY BLOCK DIAGRAM



6.2.2 LED POWER SOURCE

	Option	Power source	Jumper setting				
	A	VDD/VSS	J1,J3,R9				
LED	В	15K/16A	J2,J5,J7				
	С	A/K	NONE				
	Nil	15A/16K	J2,J4,J6				
GND	BZL GND		J8				
GND	FR	M GND	19				

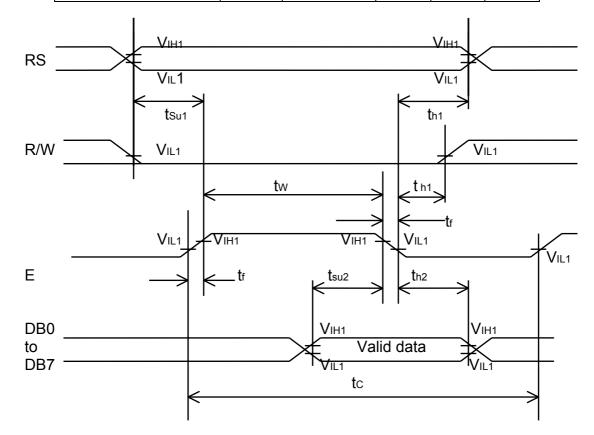
7. TIMING CHARACTERISTICS

7.1 WRITE TIMING

	AC ch	naracteristics (VI	DD=4.5v~	5.5v,Ta=-	- 30~85 °C)
Item	Symbol	Condition	Min.	Max.	Unit
E cycle time	tc		500		
E pulse width (high level)	tw		230		ns
E rise/fall time	tR, tF			20	
R/W and RS Setup time	tsu1	VDD = 5V	40		
R/W and RS Hold time	tH1		10		
Data setup time	tsu2		80		
Data hold time	tH2		10		

AC characteristics (VDD=2.7v~4.5v,Ta=-30~85°C)

Item	Symbol	Condition	Min.	Max.	Unit
E cycle time	tc		1000		
E pulse width (high level)	tw		450		
E rise/fall time	tR, tF			25	
R/W and RS Setup time	tsu1	VDD = 3V	60		ns
R/W and RS Hold time	tH1		20		
Data setup time	tsu2		195		
Data hold time	tH2		10		

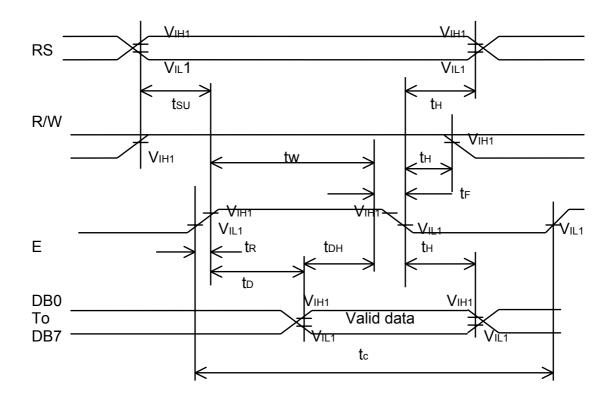


7.2 READ TIMING

Item	Symbol	Condition	Min.	Max.	Unit					
E cycle time	tc	-	500							
E pulse width (high level)	tw		230							
E rise/fall time	tR, tF			20						
R/W and RS shetup time	tsu	VDD = 5V	40		ns					
R/W and RS hold time	tH		10							
Data output delay time	tD			120						
Data hold time	tDH		5							

AC characteristics (VDD=4.5v~5.5v,Ta=-30~85°C)

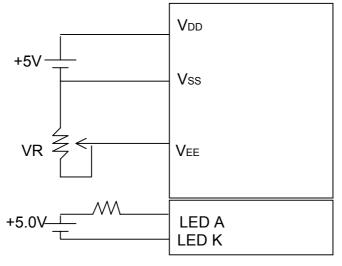
	AC ch	aracteristics (VDD=2.7v~4.5v,Ta=-30~85							
Item	Symbol	Condition	Min.	Max.	Unit				
E cycle time	tc		1000						
E pulse width (high level)	tw	1 [450						
E rise/fall time	tR, tF			25					
R/W and RS setup time	tsu	Vdd = 3V	60		ns				
R/W and RS hold time	tH		20						
Data output delay time	tD								
Data hold time	tDH		5						



8. PIN CONNECTIONS

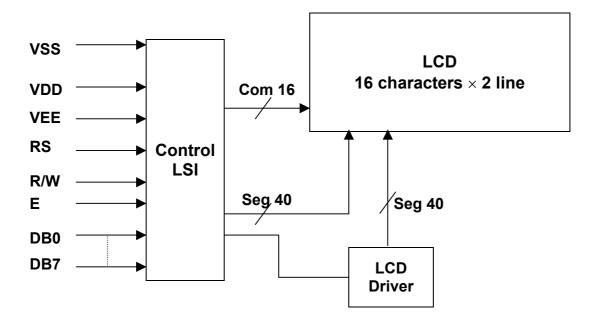
No.	Symbol	Function
1	VSS	Ground, 0V
2	VDD	Logic power supply, +5V
3	VEE	Voltage for LCD drive
4	RS	Data / Instruction register select
5	R/W	Read / Write
6	E	Enable signal, start data read/write
7	DB0	
8	DB1	
9	DB2	
10	DB3	Data Bus Line
11	DB4	
12	DB5	
13	DB6]
14	DB7	
15	LED A	LED Anode, power supply +
16	LED K	LED Cathode, ground 0V

9. POWER SUPPLY



VR = 10K

10. BLOCK DIAGRAM



Instruction		Instruction Code									DECODIDITION	Executed
Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	DESCRIPTION	Time(fosc =270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM and set DDRAM address to "00H " from AC	1.53mS
Cursor At Home	0	0	0	0	0	0	0	0	1	-	Set DDRAM address to "00H" from AC and return cursor to its original Position if shifted. The contents of DDRAM are not changed.	1.53mS
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39µS
Display On/Off Control	0	0	0	0	0	0	1	D	с	в	Set display (D), cursor(C), and Blinking of cursor(B) ON/OFF control bit.	39µS
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	-	-	Set cursor moving and display shifts cursor bit, and the direction, without changing of DDRAM data.	39µS
Function Set	0	0	0	0	1	DL	N	F	-	-	Sets interface data length (DL:8-BIT/4-BIT), number of display lines(N:2-line/1-line) and, display font type (F:5x11dots/5x8 dots).	39µS
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39µS
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39µS
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0μS
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM / CGRAM)	43µS
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Reads data from internal RAM (DDRAM / CGRAM).	43µS

10.1 INSTRUCTIONS

*"-":don't care

NOTE : When an MPU program with checking the Busy Flag(DB7) is made, it must be necessary 1/2Fosc is necessary for executing the next instruction by the falling edge of the 'E' signal after the Busy Flag(DB7)goes to "LOW".

10.2 8-Bit Operation, 8-Digit×2-Line Display Example

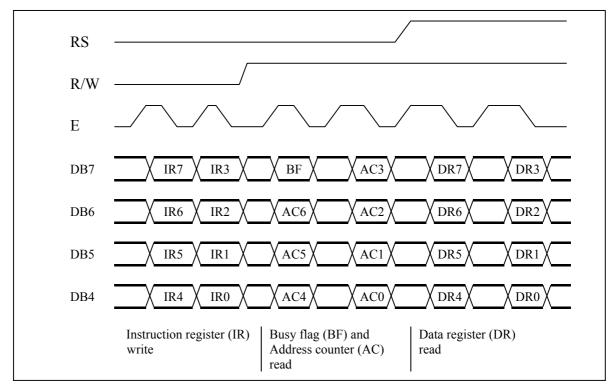
Step					Instru							
No	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
1	Power supply on (the IC is initialized by the Internal reset circuit) Initialized. No display.											
2	Fun 0	ction 0	set 0	0	1	1	1	0	*	*		Sets to 8-bit operation and selects 2-line display and 5×8 dot character font.
3	Display on/off control											Turns on display and cursor. All display is in space mode because of initialization.
4	Ent 0	ry mo 0	de set 0	0	0	0	0	1	1	0		Sets mode to increment the address by one and to shift the cursor to the right at the time of write to the DD/CGRAM.
5	Wri 1	te dat 0	ta to C 0	CGRA 1	M/DI 0	DRAN 0	1 1	0	0	0	<u>H</u>	Display is not shifted. Writes H. DDRAM has already been selected by initialization when the power was turned on. The cursor is incremented by one and shifted to the right
6						•					•	
7	Wri 1	te dat 0	ta to C 0	CGRA 1	M/DI	DRAN 0	<u>آ</u> 1	0	0	1	HITACHI_	Writes I.
8	-	v	AM ad	Idress	-	U	1	U	U	1		Sets DDRAM address so that
Ū	0	0	1	1	0	0	0	0	0	0	HITACHI _	t The cursor is positioned at the Head of the second lime.
9	Wri 1	te dat 0	ta to C 0	CGRA 1	M/DI 0	DRAN 0	1 1	1	0	1	HITACHI M_	Writes M.
10						• • •					-	
11	Wri 1	te dat 0	ta to C 0	CGRA 1	.M/DI 0	DRAN 0	1 1	1	1	1	HITACHI MICROCO_	Writes O.
12	Ent 0	ry mo 0	de set 0	0	0	0	0	1	1	1	HITACHI MICROCO_	Sets mode to shift display at the time of write.
13	Wri	te dat	ta to C	CGRA	M/DI	DRAN	1				ITACHI	Writes M. Display is shifted to the left. The first and second
	1	0	0	1	0	0	1	1	0	1	ICROCOM_	lines both shift at the same time.
14						• • •						
15	Retu 0	urn ho 0	ome 0	0	0	0	0	0	1	0	HITACHI MICROCOM	Returns both display and cursor to the original position (address 0).

10.3 Interfacing to the MPU

The IC can send data in either two 4-bit operations, thus allowing interfacing with 4-or 8-bit MPUs.

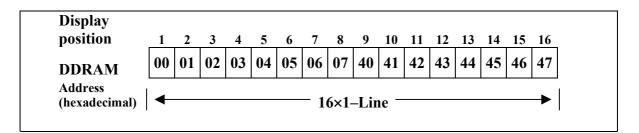
• For 4-bit interface data, only four bus lines (DB4 to DB7) are used for transfer. Bus lines DB0 to DB3 are disabled. The data transfer between the IC and the MPU is completed after the 4-bit data has been transferred twice. As for the order of data transfer, the four high order bits (for 8-bit operation, DB4 to DB7) are transferred before the four low order bits (for 8-bit operation, DB0 to DB3).

The busy flag must be checked (one instruction) after the 4-bit data has been transferred twice. Two more 4-bit operations then transfer the busy flag and address counter data.



4-Bit Transfer Example

Confidential Document 10.4 1-Line Display



2-Line Display

Display position	1	2	3	4	5	···8···16···20···24···	39	40	
DDRAM	00	01	02	03	04		26	27	
Address (hexadecimal)	40	41	42	43	44		66	67	
$ \underbrace{ 8 \times 2 - \text{Line}}_{16 \times 2 - \text{Line}} \\ \underbrace{ 20 \times 2 - \text{Line}}_{24 \times 2 - \text{Line}} \\ \underbrace{ 24 \times 2 - \text{Line}}_{24 \times 2 - \text{Line}} $									

4-Line Display

Display		2	•		15	17
position		2	3	·····	15	16
DDRAM	00	01	02		0E	0F
Address (hexadecimal)	40	41	42		4 E	4 F
	14	15	16		1E	1F
	54	55	56		5E	5F
				16×4 Line		

Display position	1	2	3		19	20
DDRAM	00	01	02		12	13
Address (hexadecimal)	40	41	42		52	53
	14	15	16		26	27
	54	55	56		66	67
	-	1	1	20×4 Line		

10.5 CGRAM

Relationship between CGRAM Addresses, Character Codes (DDRAM) and Patterns (CGRAM Data)

	-						
Character Codes	C	GR	AM	[Ad	ldre	ss	Character Patterns
(DDRAM data)	-						(CGRAM data)
7 6 5 4 3 2 1 0	5	4	3	2	1	0	7 6 5 4 3 2 1 0
High Low	Hi	gh			Lov	N	High Low
				0	0	0	* * * 1 <u>1 1 1 0</u>
				0	0	1	▲ 10001
				0	1	0	$\begin{bmatrix} 1 & 0 & 0 & 1 \\ 0 & 1 & 1 \end{bmatrix}$ Character
0 0 0 0 * 0 0 0	0	0	0	0	1	1	$ 1 1 1 1 0 \rangle$ Pattern (1)
				1	0	0	
				1	0	1	
				1	1	0	
				1	1	1	* * * 0 0 0 0 0 } Cursor position
				0	0	0	* * * 10001
				0	0	1	
				0	1	0	1 1 1 1 1 Character
0000*001	0	0	1	0	1	1	0 0 1 0 0 Pattern (2)
				1	0	0	
				1	0	1	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$
				1	1	0	
				1	1	1	* * * 0 0 0 0 0 } Cursor position
				0	0	0	
				0	0	1	
				:			
0 0 0 0 * 1 1 1	1	1	1		•	•	
				1	0 0	0 1	
				1	1	1 0	
				1	1	1	* * *
L <u> </u>					-	-	

For 5×8 dot character patterns

Notes: 1. Character code bits 0 to 2 correspond to CGRAM address bits 3 to 5 (3 bits: 8 types).

- 2. CGRAM address bits 0 to 2 designate the character pattern line position. The 8th line is the cursor position and its display is formed by a logical OR with the cursor. Maintain the 8th line data, corresponding to the cursor display position, at 0 as the cursor display.
- If the 8th line data is 1, 1 bits will light up the 8th line regardless of the cursor presence. 3. Character pattern row positions correspond to CGRAM data bits 0 to 4 (bit 4 being
- at the left). 4. As shown Table 5, CGRAM character patterns are selected when character code bits
- 4 to 7 are all 0. However, since character code bit 3 has no effect, the R display example above can be selected by either character code 00H or 08H.
- 5. 1 for CGRAM data corresponds to display selection and 0 to non-selection.
- * Indicates no effect.

10.6 Correspondence between Character Codes and Character Patterns (ROM Code:A00)

Стала Цария А. Цария — Цария А.																
	0000	0001	0010	0011	0100	0101	01 10	0111	1000	1001	1010	1011	1100	1101	11 10	1111
xxx0000	8 8 0			0	Ø	P	`	P				-	7	Ę	X	p
xxx0001	(2)		I	1	A	Q	а	9				7	Ŧ	4	ä	q
xxxx0010	(3)		П	2	В	R	b	r			Г	1	Ņ	X	ß	θ
xxxx0011	(4)		#	3	С	5	C	S			L	ゥ	Ŧ	Ð	ε.	67
xxxx0100	(5)		\$	4	D		d	t.			۰.	Ι	ŀ	Þ	Ч	Ω
xxxx0101	(6)		Ζ	5	Ε	U	е	u			-	7	Ŧ	l	G	ü
xxxx0110	7)		&	6	F	Ų	f	V			7	Ħ	_	Ξ	ρ	Σ
xxxx0111	(8)		7	7	G	Ŵ	9	W			7	Ŧ	Z	7	q	π
xxxx 1000	(1)		ζ	8	Η	X	h	X			4	2	7	Ņ	<u>,</u> Г	$\overline{\mathbf{X}}$
xxxx1001	(2)		Σ	9	Ι	Y	i	ч			÷	ን	Ţ	լի	-1	Ч
xxxx 1010	(3)		*		J	Ζ	j	Z			I		Ĥ	$\boldsymbol{\nu}$	j	Ŧ
xxxx1011	(4)		+	7	Κ		k	ł			7	ħ	F		X	Я
xxxx1100	(5)		,		L	¥	1				ħ	Ð	7	7	¢	Ħ
xxxx1101	(6)		-		Μ		M	}			ュ	Z	ኅ	2	Ł	÷
xxxx1110	7)			>	Ν	^	n	➔			E	Þ	.	~	ñ	
xxxx1111	(8)		/	?	0		0	÷			••	У	7		ö	

Note: The user can specify any pattern for character-generator RAM.

11. QUALITY ASSURANCE

11.1 Test Condition

- 11.1.1 Temperature and Humidity(Ambient Temperature) Temperature : $20 \pm 5^{\circ}C$ Humidity : $65 \pm 5\%$
- 11.1.2 Operation Unless specified otherwise, test will be conducted under function state.
- 11.1.3 Container Unless specified otherwise, vibration test will be conducted to the product itself without putting it in a container.
- 11.1.4 Test Frequency In case of related to deterioration such as shock test. It will be conducted only once.
- No. Parameter Conditions Regulations High Temperature Operating 70 ± 2 °C Note 3 1 Note 3 2 Low Temperature Operating -20 ± 2 °C High Temperature Storage 80 ± 2 °C Note 3 3 Low Temperature Storage Note 3 -30 ± 2 °C 4 Vibration Test Total fixed amplitude : 1.5mm Note 3 (Non-operation state) Vibration Frequency : 10 ~ 55Hz 5 One cycle 60 seconds to 3 directions of X.Y.Z. for each 15 minutes Damp Proof Test 40°C ± 2°C, 90~95%RH, 96h Note 1,2 6 (Non-operation state) Shock Test To be measured after dropping from Note 3 7 (Non-operation state) 60cm high once concrete surface in packing state

11.1.5 Test Method

Note 1: Returned under normal temperature and humidity for 4 hrs.

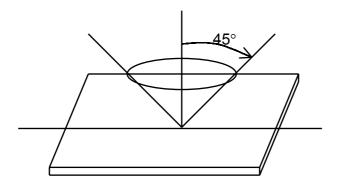
Note 2: No dew condensation to be observed.

Note 3: No change on display and in operation under the test condition

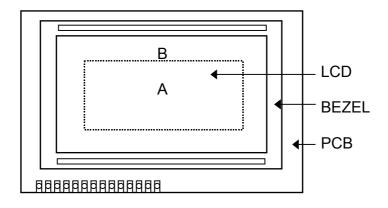
11.2 Inspection condition

11.2.1 Inspection conditions

The LCD shall be inspected under 40W white fluorescent light.



11.2.2 Definition of applicable Zones

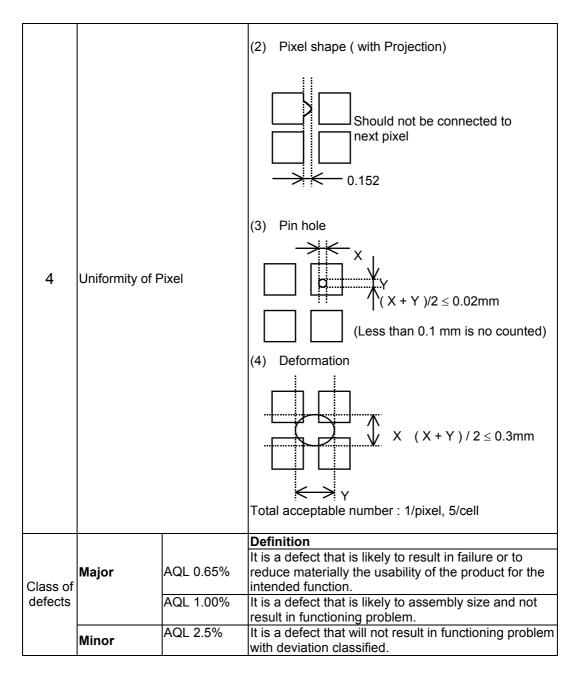


A : Display Area

B : Non-Display Area

11.2.3 Inspection Parameters

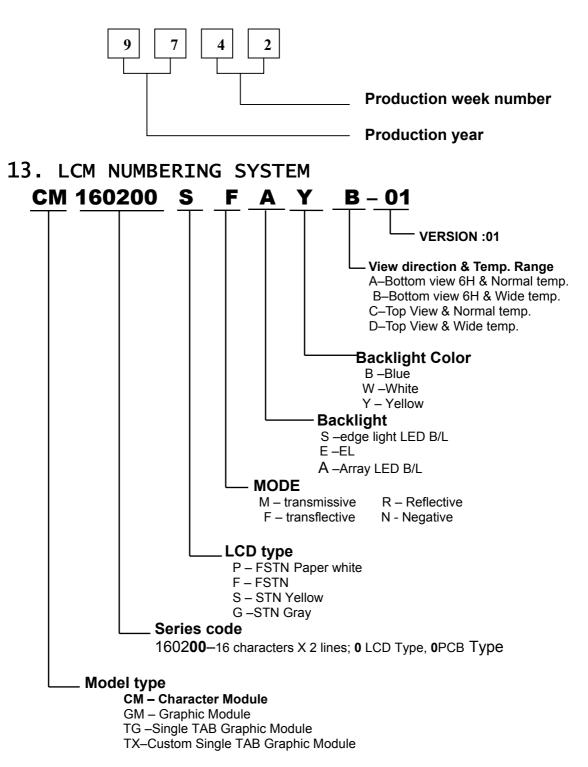
No	. Parameter	Criteria
1	Black or White spots	$\begin{array}{ c c c c c }\hline & Zone & Acceptable & Class & AQL \\ \hline Dimension & A & B & Defects \\ \hline D < 0.15 & * & * & \\ \hline 0.15 \le D < 0.2 & 4 & 4 & \\ \hline 0.2 \le D \le 0.25 & 2 & 2 & \\ \hline D \le 0.3 & 0 & 1 & \\ \hline \end{array} \begin{array}{ c c c }\hline & & & & \\ \hline & & & & \\ \hline & & & & \\ \hline & & & &$
2	Scratch, Substances	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$
3	Air Bubbles (between glass & polarizer)	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$
4	Uniformity of Pixel	(1) Pixel shape (with Dent) 0.152



11.3 Sampling Condition

Unless otherwise agree in written, the sampling inspection shall be applied to the incoming inspection of customer. Lot size: Quantity of shipment lot per model. Sampling type: normal inspection, single sampling Inspection level: Level II Sampling table: MIL-STD-105E

12. LOT NUMBERING SYSTEM



14. PRECAUTION FOR USING LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing,

(1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause

polarization degredation, polarizer peel off or bubble.

(2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface, wipe gently with cotton, chamois or other soft material soaked in petroleum benzin.

(3). Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.

(4). Glass can be easily chipped or cracked from rough handling, especially at corners and edges.

(5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted. (1). Do not tamper in any way with the tabs on the metal frame.

(2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattern.

(3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).

(4). When mounting a LCM make sure that the PCB is not under any stress such as bending or twisting . Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.

(5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

(2). The modules should be kept in antistatic bags or other containers resistant to static for storage.

(3). Only properly grounded soldering irons should be used.

(4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

(5) The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.(6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

2.3 Soldering

(1). Solder only to the I/O terminals.

(2). Use only soldering irons with proper grounding and no leakage.

(3). Soldering temperature : $280^{\circ}C \pm 10^{\circ}C$

(4). Soldering time: 3 to 4 sec.

(5). Use eutectic solder with resin flux fill.

(6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4 Operation

(1). The viewing angle can be adjusted by varying the LCD driving voltage V0.

(2). Driving voltage should be kept within specified range; excess voltage shortens display life.

(3). Response time increases with decrease in temperature.

(4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".

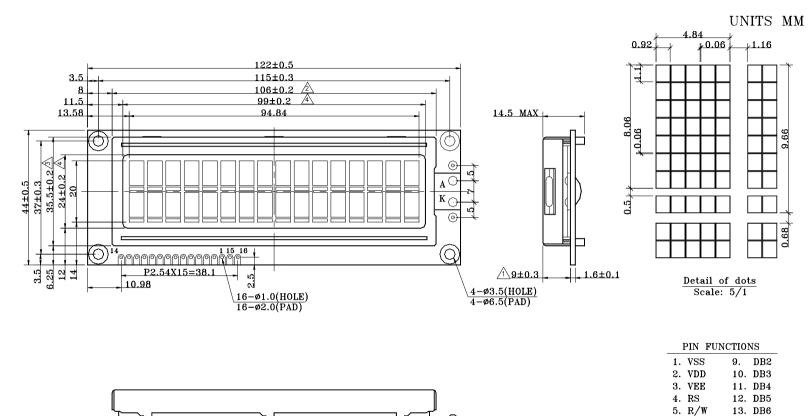
(5). Mechanical disturbance during operation (such as pressing on the viewing area) may cause the segments to appear "fractured".

2.5 Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6 Limited Warranty

Unless otherwise agreed between DATA IMAGE and customer, DATA IMAGE will replace or repair any of its LCD and LCM which is found to be defective electrically and visually when inspected in accordance with DATA IMAGE acceptance standards, for a period on one year from date of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of DATA IMAGE is limited to repair and/or replacement on the terms set forth above. DATA IMAGE will not responsible for any subsequent or consequential events. 15. OUTLINE DRAWING





Note: tolerance is ± 0.3 unless otherwise noted.

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14. DB7 15. LEDA

16. LEDK

6. E

7. DB0

8. DB1

